L Number	Hits	Search Text	DB	Time stamp
1	33	((recognition$4 adj mark$4) with (via or through-hole or (through adj hole) or throughhole contact bump plated plating)) with (wiring circuit circuity ic socket metal metallization conducting conductive conductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 17:04
-	1429	recognition$4 adj mark$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 16:59
-	77	(recognition$4 adj mark$4) with (via or through-hole or (through adj hole) or throughhole contact bump plated plating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 16:59